

7-CHANNEL VIDEO SWITCH

 Check for Samples: [TS3V712E](#)

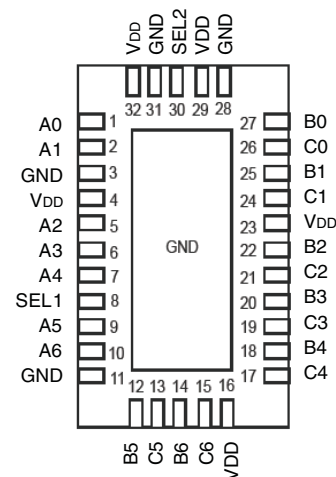
FEATURES

- High Bandwidth (BW = 1.36 GHz)
- Designed for 7-Channel VGA Signals (R,G,B, H_{sync}, V_{sync}, DDC Dat, and DDC CLK)
- Separate Control Logic for Data and Control Signals
- Operating Voltage: 3.3 V ±10%
- Low and Flat ON-State Resistance
 - r_{ON} = 3 Ω
 - r_{ON(flat)} = 500 mΩ
- Low Crosstalk (X_{TALK} = -49.76 dB Typ at 250 MHz)
- Low Input/Output Capacitance
 - C_{ON} = 7 pF, Typ
- ESD Performance Tested
 - 4-kV IEC61000-4-2, Contact Discharge on Switch IOs
 - 3-kV Human Body Model Per JESD22-A114E
 - 6-kV Human Body Model (Switch Pins to GND)
- Suitable for Both RGB and Composite-Video Switching

- 32-Pin Quad Flat Pack No-Lead QFN(RTG) Package

APPLICATIONS

- Notebook Computers
- Analog VGA Peripheral Ports

**RTG PACKAGE
(TOP VIEW)**


The exposed center pad must be connected to GND.

DESCRIPTION/ORDERING INFORMATION

The TS3V712E is a high-bandwidth, 7-channel video multiplexer/demultiplexer for switching between multiple VGA sources or end points. The device is designed for ensuring video signal integrity and minimizing the video signal attenuation by providing high bandwidth of 1.36 GHz.

The video signals are protected against high ESD with integrated diodes to V_{DD} and GND that will support up to 6-kV of ESD HBM and 4-kV contact protection.

The TS3V712E is available in a 32-pin QFN package and is characterized for operation over the free-air temperature range of -40°C to 85°C.

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾ (2)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RTG Tape and reel	TS3V712ERTGR	TF712E

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LOGIC DIAGRAM

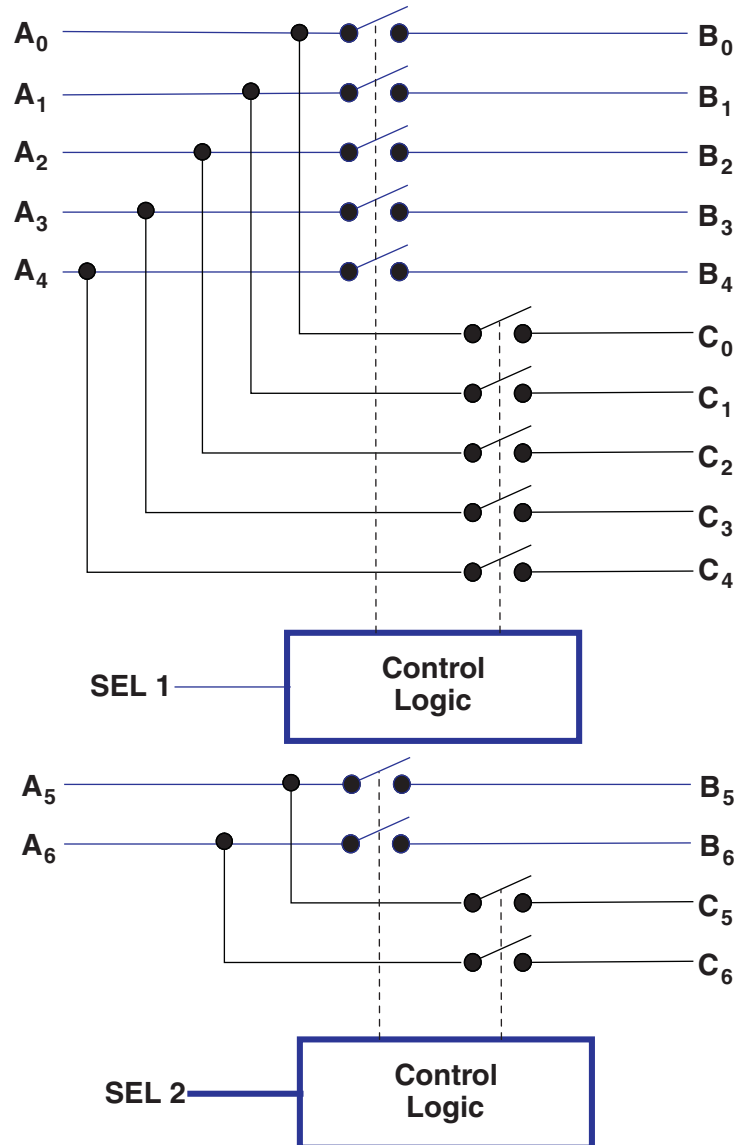


Table 1. FUNCTION TABLE

SEL1	SEL2	FUNCTION		
		A0–A4	A5, A6	Hi-Z
L	L	B0–B4	B5, B6	Cn
L	H	B0–B4	C5, C6	C0–C4, B5, B6
H	L	C0–C4	B5, B6	B0–B4, C5, C6
H	H	C0–C4	C5, C6	Bn

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{DD}	Supply voltage range		-0.5	4.6	V
V _{IN}	Control input voltage range ⁽²⁾ ⁽³⁾	SEL	-0.5	7	V
V _{I/O}	Switch I/O voltage range ⁽²⁾ ⁽³⁾ ⁽⁴⁾	All I/O ports	-0.5	7	V
I _{IK}	Control input clamp current	V _{IN} < 0 V		-50	mA
I _{I/OK}	I/O port clamp current	V _{I/O} < 0 V		-50	mA
I _{I/O}	ON-state switch current ⁽⁵⁾	ON-state switch		±128	mA
	Continuous current through V _{DD} or GND			±100	mA
θ _{JA}	Package thermal impedance	RTG package ⁽⁶⁾		39.2	°C/W
T _{stg}	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to ground, unless otherwise specified.
- (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (4) V_I and V_O are used to denote specific conditions for V_{I/O}.
- (5) I_I and I_O are used to denote specific conditions for I_{I/O}.
- (6) The package thermal impedance is calculated in accordance with JESD 51-5 (High K with via).

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			MIN	MAX	UNIT
V _{DD}	Supply voltage		3	3.6	V
V _{IN}	Control input voltage (SEL)		0	5.5	V
V _{IH}	High-level control input voltage (SEL)		2		V
V _{IL}	Low-level control input voltage (EN, IN)		-0.5	0.8	V
V _{I/O}	I/O voltage (all ports)		0	V _{DD}	V
T _A	Operating free-air temperature		-40	85	°C

- (1) All unused control inputs of the device must be held at V_{DD} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

ELECTRICAL CHARACTERISTICS⁽¹⁾

for high-frequency switching over recommended operating free-air temperature range, $V_{DD} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS				MIN	TYP ⁽²⁾	MAX	UNIT
V_{IK}	SEL n	$V_{DD} = 3.6 \text{ V}$,	$I_{IN} = -18 \text{ mA}$			-0.7	-1.2	V	
I_{IH}	SEL n	$V_{DD} = 3.6 \text{ V}$,	$V_{IN} = V_{DD}$				± 1	μA	
I_{IL}	SEL n	$V_{DD} = 3.6 \text{ V}$,	$V_{IN} = \text{GND}$				± 1	μA	
I_{OFF}		$V_{DD} = 0 \text{ V}$,	$V_O = 0 \text{ to } 3.6 \text{ V}$,	$V_I = 0$,	$V_{IN} = 0$		1	μA	
I_{CC}		$V_{DD} = 3.6 \text{ V}$,	$I_{I/O} = 0$,	$V_{IN} = V_{DD}$ or GND,	Switch ON or OFF	200	500	μA	
C_{IN}	SEL n	$f = 10 \text{ MHz}$	$V_{IN} = 0$,			2.7	3	pF	
C_{OFF}	3 ports	$f = 10 \text{ MHz}$	$V_{IN} = 0$,	Output open,	Switch OFF	3	4	pF	
C_{ON}	3 ports	$f = 10 \text{ MHz}$	$V_{IN} = 0$,	Output open,	Switch ON	7		pF	
r_{ON}		$V_{DD} = 3 \text{ V}$,	$0 \text{ V} \leq V_I \leq 1.2 \text{ V}$,	$I_{I/O} = -40 \text{ mA}$		3	4	Ω	
$r_{ON(\text{flat})}$ ⁽³⁾		$V_{DD} = 3 \text{ V}$,	$V_I = 0 \text{ V and } 1.2 \text{ V}$	$I_{I/O} = -40 \text{ mA}$		0.5	1	Ω	
Δr_{ON} ⁽⁴⁾		$V_{DD} = 3 \text{ V}$,	$0 \text{ V} \leq V_I \leq 1.2 \text{ V}$,	$I_{I/O} = -40 \text{ mA}$		0.1	1	Ω	

- (1) V_I , V_O , I_I , and I_O refer to I/O pins. V_{IN} refers to the control inputs.
(2) All typical values are at $V_{DD} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.
(3) $r_{ON(\text{flat})}$ is the difference of r_{ON} in a given channel at specified voltages.
(4) Δr_{ON} is the difference of r_{ON} from center port to any other ports.

DYNAMIC CHARACTERISTICS

over recommended operating free-air temperature range, $V_{DD} = 3.3 \text{ V} \pm 0.3 \text{ V}$, $R_L = 50 \Omega$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS			TYP ⁽¹⁾	UNIT
X_{TALK}	$R_L = 50 \Omega$,	$f = 250 \text{ MHz}$,	See Figure 7	-49.76	dB
O_{IRR}	$R_L = 50 \Omega$,	$f = 250 \text{ MHz}$,	See Figure 8	-37.51	dB
BW	See Figure 6			1.36	GHz

- (1) All typical values are at $V_{CC} = 5 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{DD} = 3.3 \text{ V} \pm 0.3 \text{ V}$, $R_L = 50 \Omega$, $T_A = 25^\circ\text{C}$ (unless otherwise noted) (see [Figure 5](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP	MAX	UNIT
t_{pd} ⁽¹⁾	An or Bn/Cn	Bn/Cn or An		0.25		ns
t_{PZH} , t_{PZL} ⁽²⁾	SEL	Bn or Cn	0.5		12	ns
t_{PHZ} , t_{PLZ} ⁽³⁾	SEL	Bn or Cn	0.5		11	ns
$t_{sk(o)}$ ⁽⁴⁾	An, Bn, Cn			0.05	0.1	ns
$t_{sk(p)}$ ⁽⁵⁾	An, Bn, Cn			0.05	0.1	ns

- (1) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance when driven by an ideal voltage source (zero output impedance).
(2) Line enable time: SEL to input, output; also called as SEL to switch turn on time.
(3) Line disable time: SEL to input, output; also called as SEL to switch turn off time.
(4) Output skew between center port to any other ports.
(5) Skew between opposite transitions of the same output. $|t_{PHL} - t_{PLH}|$

TYPICAL CHARACTERISTICS

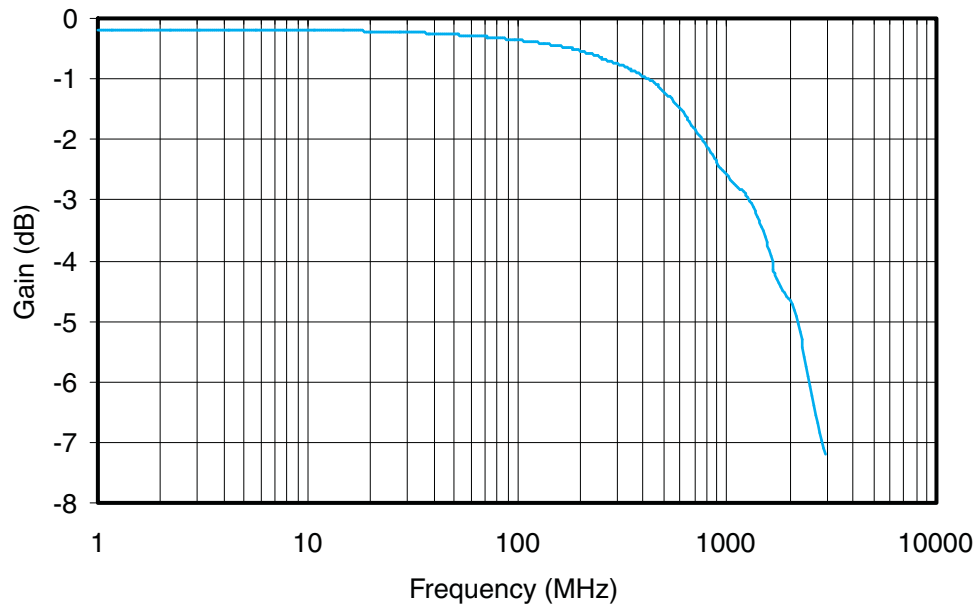


Figure 1. Gain vs Frequency

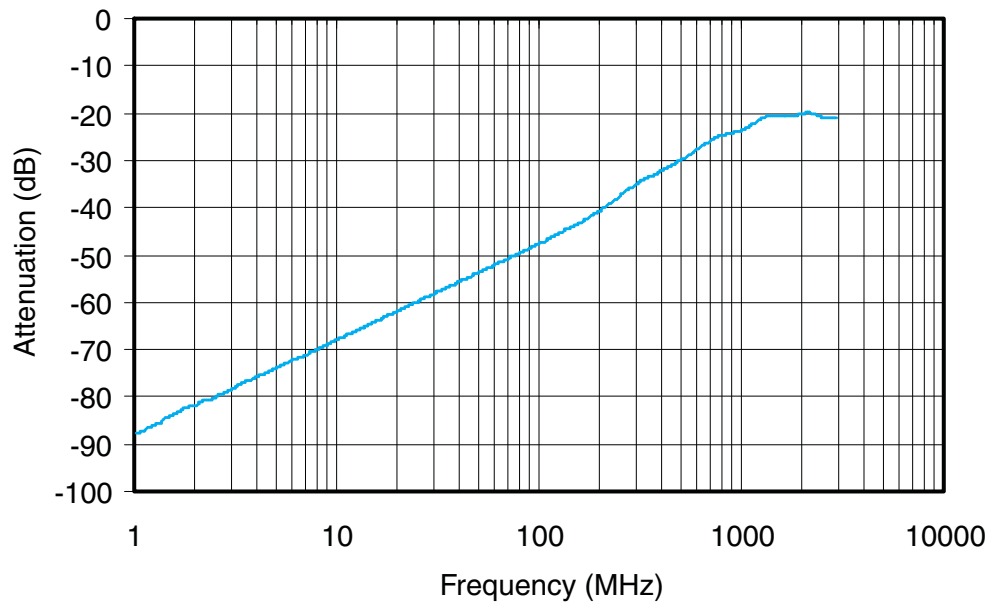


Figure 2. Off Isolation vs Frequency

TYPICAL CHARACTERISTICS (continued)

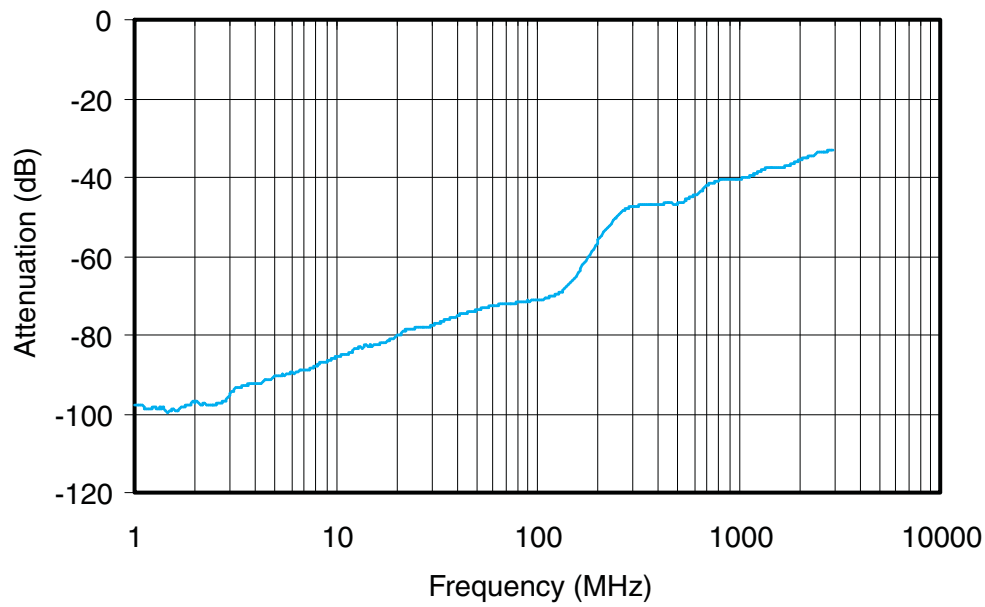


Figure 3. Crosstalk vs Frequency

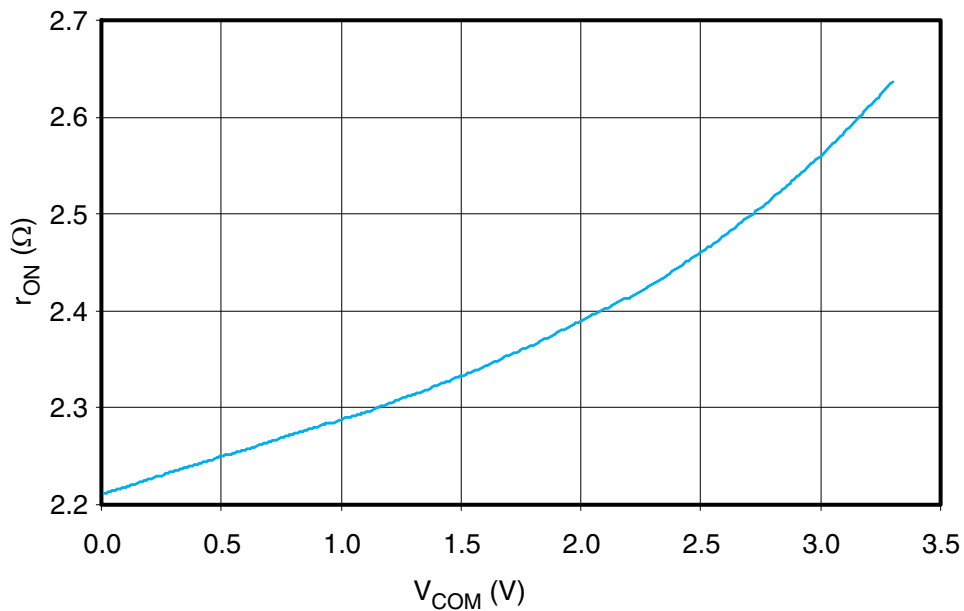
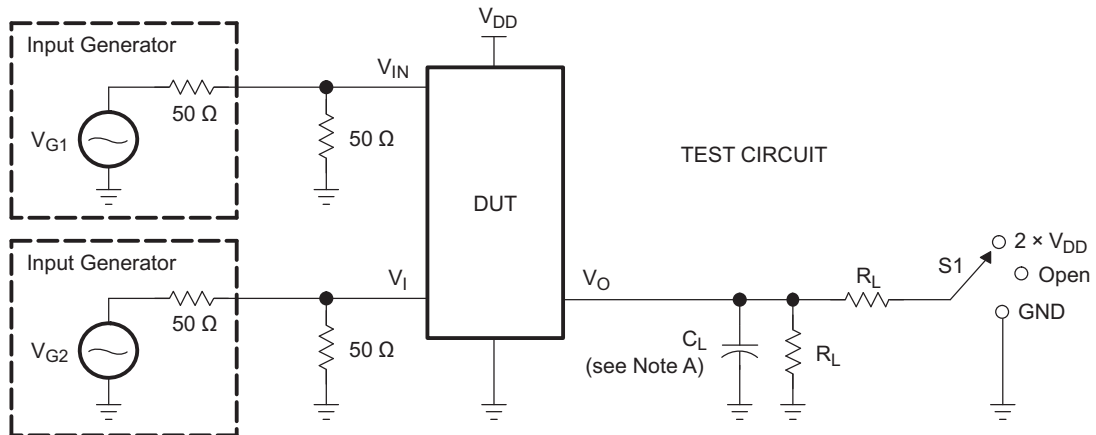
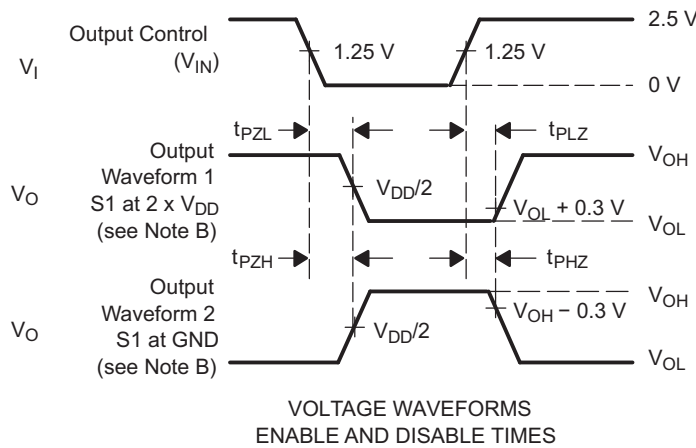


Figure 4. r_{ON}(Ω) vs V_{COM}(V)

PARAMETER MEASUREMENT INFORMATION



TEST	V _{DD}	S1	R _L	V _{in}	C _L	V _Δ
t _{PLZ} /t _{PZL}	3.3 V	2 × V _{DD}	200 Ω	GND	10 pF	0.3 V
t _{PHZ} /t _{PZH}	3.3 V	GND	200 Ω	V _{DD}	10 pF	0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR = 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 F. t_{PZL} and t_{PZH} are the same as t_{en}.

Figure 5. Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION (continued)

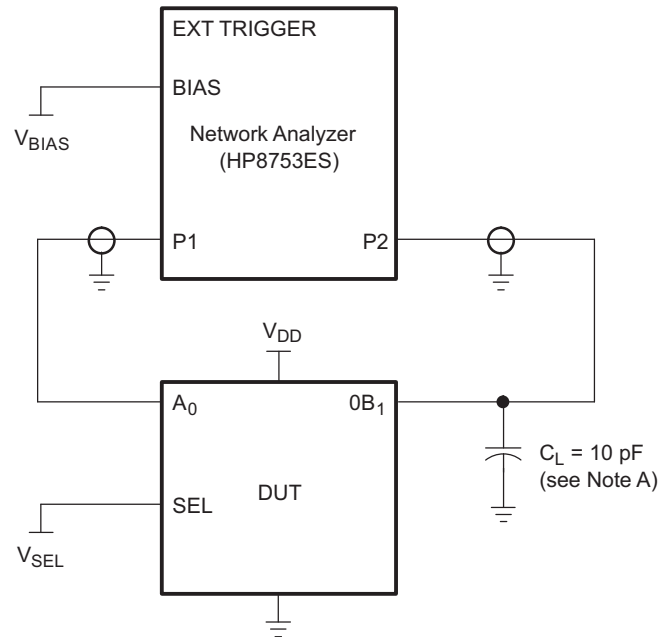


Figure 6. Test Circuit for Frequency Response (BW)

Frequency response is measured at the output of the ON channel. For example, when $V_{SEL} = 0$ and A_0 is the input, the output is measured at $0B1_1$. All unused analog I/O ports are left open.

HP8753ES Setup

Average = 4
 RBW = 3 kHz
 $V_{BIAS} = 0.35$ V
 ST = 2 s
 P1 = 0 dBm

PARAMETER MEASUREMENT INFORMATION (continued)

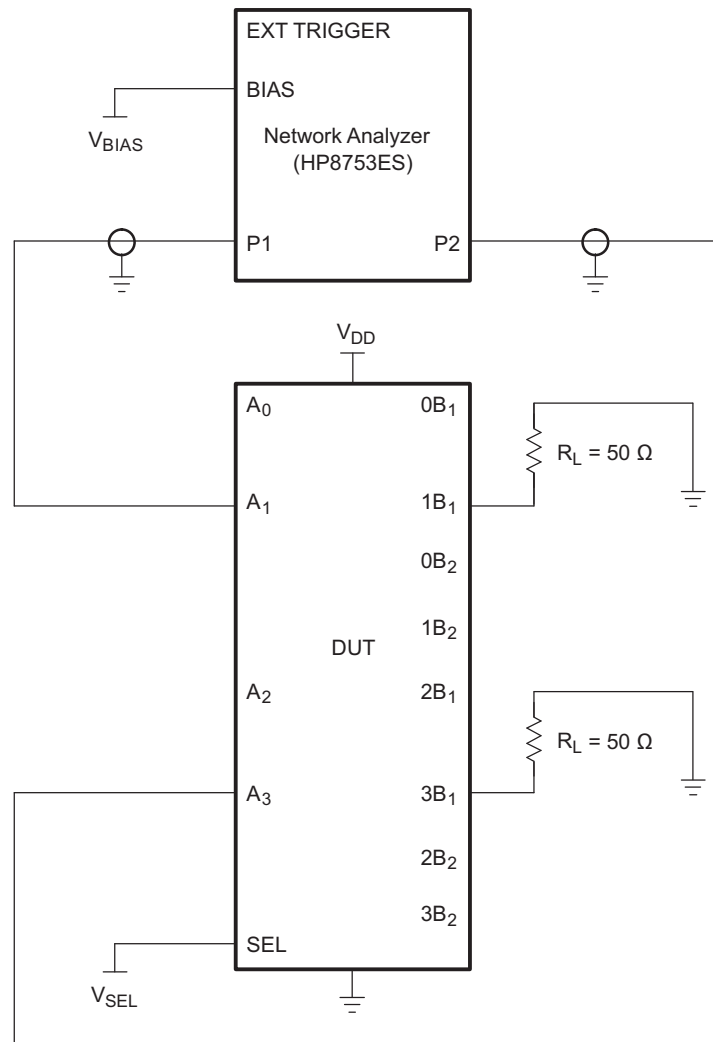


Figure 7. Test Circuit for Crosstalk (X_{TALK})

Crosstalk is measured at the output of the nonadjacent ON channel. For example, when $V_{IN} = 0$, $V_{EN} = 0$, and D_A is the input, the output is measured at $S1_B$. All unused analog input (D) ports and output (S) ports are connected to GND through 10- Ω and 50- Ω pulldown resistors, respectively.

HP8753ES Setup

- Average = 4
- RBW = 3 kHz
- $V_{BIAS} = 0.35$ V
- ST = 2 s
- P1 = 0 dBm

PARAMETER MEASUREMENT INFORMATION (continued)

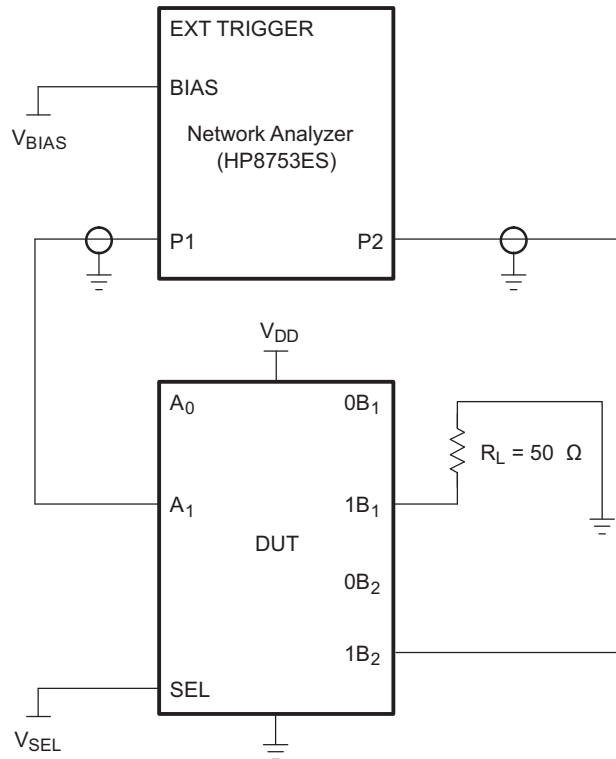


Figure 8. Test Circuit for Off Isolation (O_{IRR})

Off isolation is measured at the output of the OFF channel. For example, when $V_{IN} = V_{CC}$, $V_{EN} = 0$, and D_A is the input, the output is measured at $S1_A$. All unused analog input (D) ports are left open, and output (S) ports are connected to GND through 50- Ω pulldown resistors.

HP8753ES Setup

Average = 4
 RBW = 3 kHz
 $V_{BIAS} = 0.35$ V
 ST = 2 s
 P1 = 0 dBm

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TS3V712ERTGR	ACTIVE	WQFN	RTG	32	3000	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	TF712E	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS3V712ERTGR	WQFN	RTG	32	3000	330.0	16.4	3.3	6.3	1.0	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

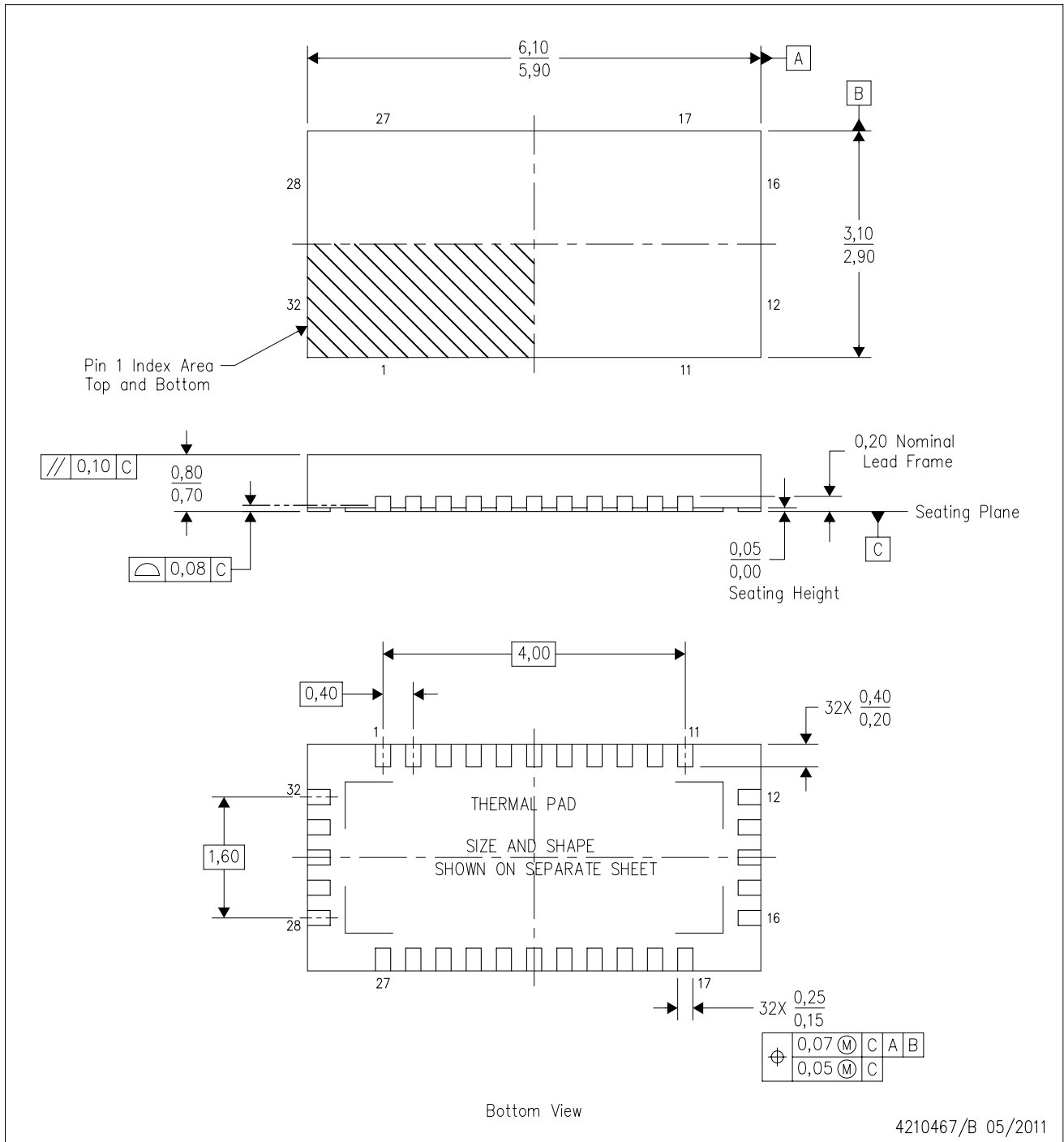

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS3V712ERTGR	WQFN	RTG	32	3000	853.0	449.0	35.0

MECHANICAL DATA

RTG (R-PWQFN-N32)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Reference JEDEC MO-220.

THERMAL PAD MECHANICAL DATA

RTG (R-PWQFN-N32)

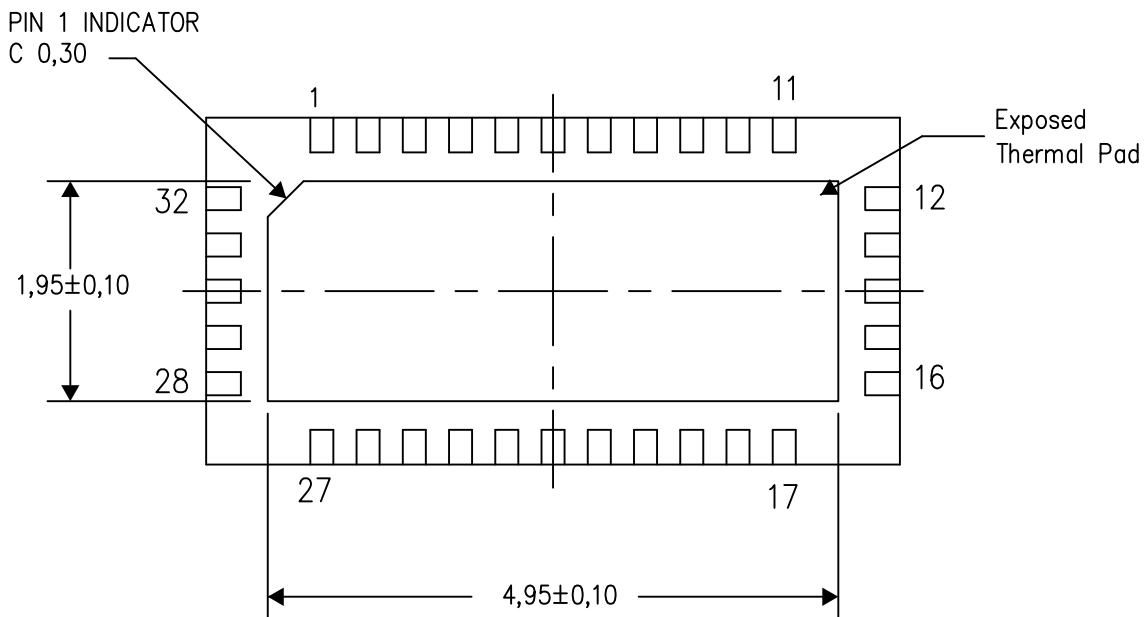
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

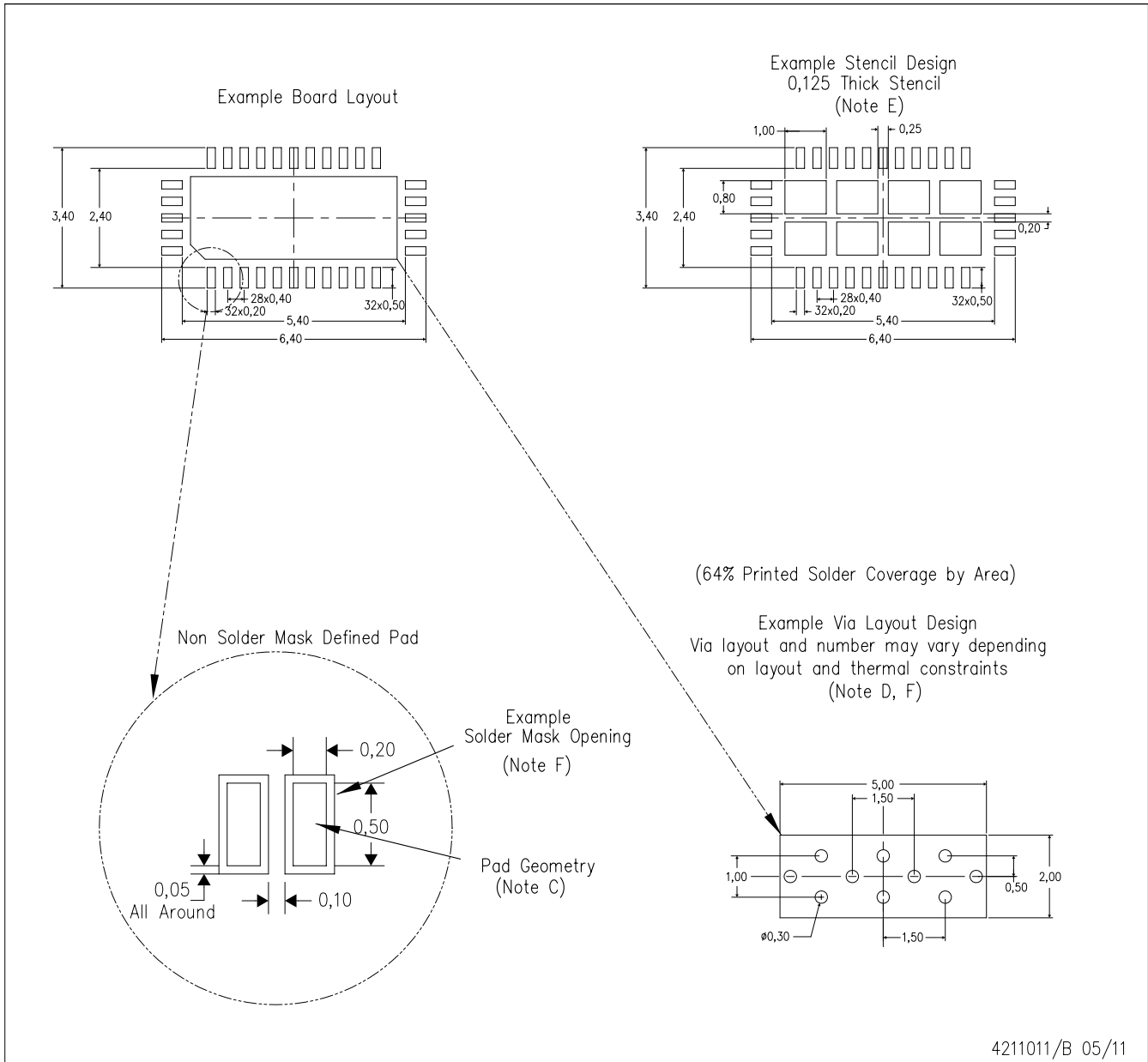
Exposed Thermal Pad Dimensions

4210534-2/D 12/13

NOTE: All linear dimensions are in millimeters

RTG (R-PWQFN-N32)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SCBA017, SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2020, Texas Instruments Incorporated